

Claims

~~{Claim 1}~~

~~— A polishing pad comprising a substrate and a resin portion provided on the substrate,~~

~~— the resin portion comprising a resin-based compound and fixed abrasive grains contributing to polishing of a workpiece to be polished.~~

~~{Claim 2}~~

~~— The polishing pad according to claim 1, wherein~~

~~— the resin-based compound has an acid value of 50 to 200 KOHmg/g.~~

~~{Claim 3}~~

~~— The polishing pad according to claim 1 or 2, wherein~~

~~— the resin portion further comprises a resin of a resin-based compound, and~~

~~— the resin comprises an acrylic phenolic resin.~~

~~{Claim 4}~~

~~— The polishing pad according to any one of claims 1 to 3, wherein~~

~~— the fixed abrasive grains comprise at least one selected from the group consisting of diamond abrasive grains, cerium oxide abrasive grains, alumina abrasive grains, silicon carbide abrasive grains, silicon oxide abrasive grains, zirconia abrasive grains, iron oxide abrasive grains, manganese oxide abrasive grains, magnesium oxide abrasive grains, calcium oxide abrasive~~

~~grains, barium oxide abrasive grains, zinc oxide abrasive grains, barium carbonate abrasive grains, and calcium carbonate abrasive grains.~~

~~{Claim 5}~~

~~—— The polishing pad according to claim 3 or 4, wherein
—— a content of the resin of the resin-based compound is 5 to 45% by mass based on the total amount of the resin portion.~~

~~{Claim 6}~~

~~—— The polishing pad according to any one of claims 1 to 5, wherein
—— a content of the resin-based compound is 2.5 to 50% by mass based on the total amount of the resin portion.~~

~~{Claim 7}~~

~~—— The polishing pad according to any one of claims 1 to 6, wherein
—— a content of the fixed abrasive grains is 30 to 60% by mass based on the total amount of the resin portion.~~

~~{Claim 8}~~

~~—— The polishing pad according to any one of claims 1 to 7, wherein
—— the substrate comprises a polyester-based film.~~

~~{Claim 9}~~

~~—— The polishing pad according to any one of claims 1 to 8, further comprising
—— an adhesive layer on a side of the substrate opposite to the resin portion.~~

~~{Claim 10}~~

~~—— A method for producing a polishing pad, comprising:
—— an adhering step of adhering a curable composition
onto a substrate, the curable composition comprising a
resin-based compound and fixed abrasive grains
contributing to polishing of a workpiece to be polished;
and
—— a curing step of curing the adhered curable
composition to obtain a resin portion.~~

~~{Claim 11}~~

~~—— A method for producing a polishing-processed product,
comprising
—— a polishing step of polishing a workpiece to be
polished by use of the polishing pad according to any one
of claims 1 to 9.~~

[Claim 1]

A polishing pad comprising a substrate and a resin portion provided on the substrate,

the resin portion comprising a rosin-based compound and fixed abrasive grains contributing to polishing of a workpiece to be polished,

the rosin-based compound has an acid value of 50 to 150 KOHmg/g.

[Claim 2]

The polishing pad according to claim 1, wherein the resin portion further comprises a resin other than a rosin-based compound, and

the resin comprises an acrylic phenolic resin.

[Claim 3]

The polishing pad according to claim 1 or 2, wherein the fixed abrasive grains comprise at least one selected from the group consisting of diamond abrasive grains, cerium oxide abrasive grains, alumina abrasive grains, silicon carbide abrasive grains, silicon oxide abrasive grains, zirconia abrasive grains, iron oxide abrasive grains, manganese oxide abrasive grains, magnesium oxide abrasive grains, calcium oxide abrasive grains, barium oxide abrasive grains, zinc oxide abrasive grains, barium carbonate abrasive grains, and calcium carbonate abrasive grains.

[Claim 4]

The polishing pad according to claim 2 or 3, wherein
a content of the resin other than the rosin-based
compound is 5 to 45% by mass based on the total amount of
the resin portion.

[Claim 5]

The polishing pad according to any one of claims 1
to 4, wherein
a content of the rosin-based compound is 2.5 to 50%
by mass based on the total amount of the resin portion.

[Claim 6]

The polishing pad according to any one of claims 1
to 5, wherein
a content of the fixed abrasive grains is 30 to 60%
by mass based on the total amount of the resin portion.

[Claim 7]

The polishing pad according to any one of claims 1
to 6, wherein
the substrate comprises a polyester-based film.

[Claim 8]

The polishing pad according to any one of claims 1
to 7, further comprising

an adhesive layer on a side of the substrate
opposite to the resin portion.

[Claim 9]

A method for producing a polishing pad, comprising:
an adhering step of adhering a curable composition
onto a substrate, the curable composition comprising a
rosin-based compound having an acid value of 50 to 150
KOHmg/g and fixed abrasive grains contributing to
polishing of a workpiece to be polished; and
a curing step of curing the adhered curable
composition to obtain a resin portion.

[Claim 10]

A method for producing a polishing-processed product,
comprising
a polishing step of polishing a workpiece to be
polished by use of the polishing pad according to any one
of claims 1 to 8.